-			1 1 1	
<sup>2</sup> Tyco Electronics	Our commitment. Your advantage.			Search
Products Documentation	Resources My Account Cu	ustomer Support		
Home > Products > By Type > Socket/(	Card Products > Product Feature Select	tor > Product Details		
320 - AG11D - ESL-LF Pro	duct Details			Live Product Chat US O
				Live Product Chat US O 8:30am - Spm ET, Mon - Fr Quick Links
DIP Sockets Always EU RoHS/ELV Complia Always EU RoHS/ELV Complia Product Highlights: ○ DIP Socket ○ Number of Positions = 20 ○ Row-to - Row Spacing = 7.0 ○ Thru Hole ○ Mount Style = Vertical View all Features   Find Products		.62 mm	mpliance)	Check Pricing & Availability Search for Tooling Product Feature Selector Contact Us About This Product
Documentation & Additional	Information			
Product Drawings: <sup>o</sup> OPEN FRAME DIP. ECONOMY (STAMPED CONTACT) ( (PDF, English)		T) (REF AUGA	Additional Information:   ? Product Line Information	
Catalog Pages/Data Sheets:			Related Products: <sup>7</sup> Tooling	
? None Available				
Product Specifications: 2 None Available				
Application Specifications: 2 None Available				
Instruction Sheets:				
CAD Files: (CAD Format & C ? 2D Drawing_(DXF, Vers ? 3D ModeL (IGES, Versio ? 3D ModeL (STEP, Versi	sion E2) on E2)			
	L	ist all Documents		
Product Features (Please use t	he Product Drawing for all design activity)			
Product Type Features: Product Type _ = DIP Socket Number of Positions _ = 20 Profile = Standard Frame Style _ = Ladder Leg Style _ = Straight Sleeve Material = Brass Product Series = 800 Series Electrical Characteristics: Insulation Resistance (M?) = 5,000 Contact Resistance (M?) = 5,000 Contact Resistance (M?) = 10 Termination Related Features: Termination Related Features: Solder Tail Contact Plating = Tin Body Related Features: Row-to -Row Spacing (mm [in]) _ = 7.62 [0.300] Mount Style _ = Vertical Centerline (mm [in]) _ = 2.54 [0.100]		Contact Related Features: • Contact Mount = Thru Hole • Contact Material = Beryllium Copper • Contact Mating Area Plating Material = Gold (s • Contact Style = Stamped + Formed • Mating Contact Type = Four - Fingered Configuration Related Features: • Height Above PC Board (mm [in]) = 2.67 [0.105] Industry Standards: • RoHS/ELV Compliance = RoHS compliant, ELV compliant • Lead Free Solder Processes = Wave solder capable to 240°C, Wave solder capable to 260° C, Wave solder capable to 265°C • RoHS/ELV Compliance History = Always was RoHS compliant Conditions for Usage: • Temperature Range (°C) = 125 Packaging Related Features: • Packaging Method = Tube		
		Packaging M	lethod = lub	e

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